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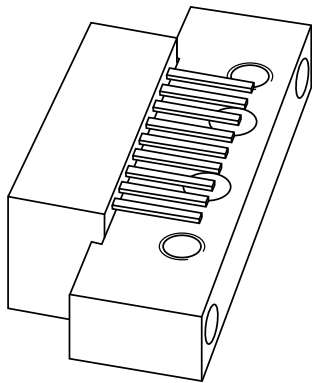
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# DATA SHEET



## **BGD885**

860 MHz, 17 dB gain power  
doubler amplifier

Product specification  
Supersedes data of 2001 Oct 25

2001 Nov 02



# 860 MHz, 17 dB gain power doubler amplifier

**BGD885**

**FEATURES**

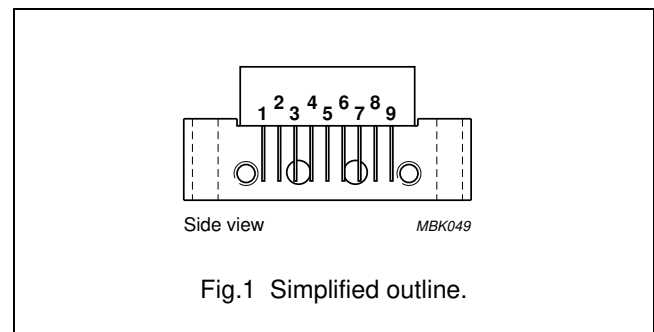
- Excellent linearity
- Extremely low noise
- Silicon nitride passivation
- Rugged construction
- Gold metallization ensures excellent reliability.

**DESCRIPTION**

Hybrid amplifier module for CATV/MATV systems operating over a frequency range of 40 to 860 MHz at a voltage supply of 24 V (DC).

**PINNING - SOT115D**

PIN	DESCRIPTION
1	input
2, 3, 5, 6, 7	common
4	10 V, 200 mA supply terminal
8	+V <sub>B</sub>
9	output



**QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
G <sub>p</sub>	power gain	f = 50 MHz	16.5	17.5	dB
I <sub>tot</sub>	total current consumption (DC)	V <sub>B</sub> = 24 V	–	450	mA

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V <sub>B</sub>	DC supply voltage	–	26	V
V <sub>i</sub>	RF input voltage	–	65	dBmV
T <sub>stg</sub>	storage temperature	–40	+100	°C
T <sub>mb</sub>	operating mounting base temperature	–20	+100	°C

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### CHARACTERISTICS

**Table 1** Bandwidth 40 to 860 MHz;  $V_B = 24$  V;  $T_{mb} = 35$  °C;  $Z_S = Z_L = 75$   $\Omega$

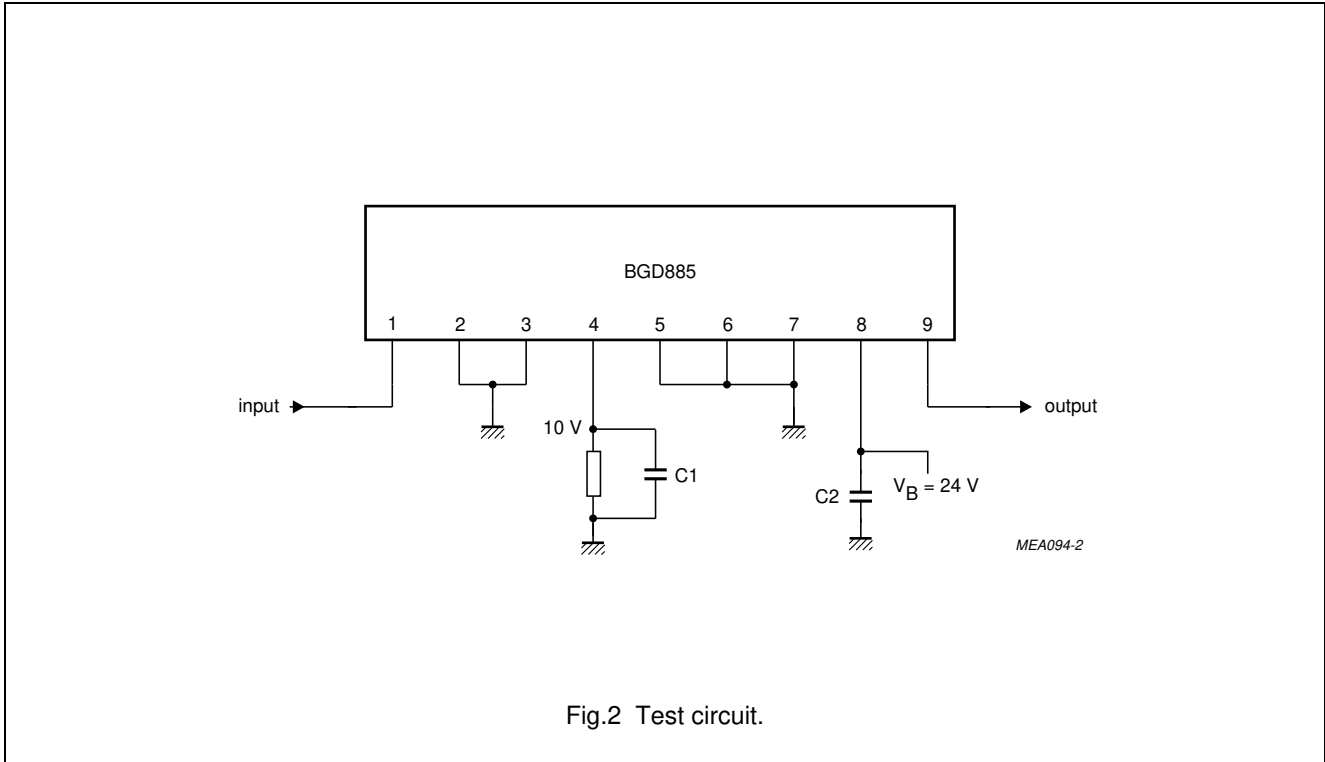
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$G_p$	power gain	$f = 50$ MHz	16.5	17.5	dB
SL	slope cable equivalent	$f = 40$ to 860 MHz	0.2	1.6	dB
FL	flatness of frequency response	$f = 40$ to 860 MHz	–	$\pm 0.5$	dB
$S_{11}$	input return losses	$f = 40$ MHz; note 1	20	–	dB
		$f = 800$ to 860 MHz	10	–	dB
$S_{22}$	output return losses	$f = 40$ MHz; note 1	20	–	dB
		$f = 800$ to 860 MHz	10	–	dB
$d_2$	second order distortion	note 2	–	–53	dB
$V_o$	output voltage	$d_{im} = -60$ dB; note 3	64	–	dBmV
		$d_{im} = -60$ dB; note 4	63	–	dBmV
F	noise figure	$f = 50$ MHz	–	8	dB
		$f = 550$ MHz	–	8	dB
		$f = 650$ MHz	–	8	dB
		$f = 750$ MHz	–	8	dB
		$f = 860$ MHz	–	8	dB
$I_{tot}$	total current consumption (DC)	note 5	–	450	mA

### Notes

- Decrease per octave of 1.5 dB.
- $V_p = 59$  dBmV at  $f_p = 349.25$  MHz;  
 $V_q = 59$  dBmV at  $f_q = 403.25$  MHz;  
measured at  $f_p + f_q = 752.5$  MHz.
- Measured according to DIN45004B:  
 $f_p = 341.25$  MHz;  $V_p = V_o$ ;  
 $f_q = 348.25$  MHz;  $V_q = V_o - 6$  dB;  
 $f_r = 350.25$  MHz;  $V_r = V_o - 6$  dB;  
measured at  $f_p + f_q - f_r = 339.25$  MHz.
- Measured according to DIN45004B:  
 $f_p = 851.25$  MHz;  $V_p = V_o$ ;  
 $f_q = 858.25$  MHz;  $V_q = V_o - 6$  dB;  
 $f_r = 860.25$  MHz;  $V_r = V_o - 6$  dB;  
measured at  $f_p + f_q - f_r = 849.25$  MHz.
- The module normally operates at  $V_B = 24$  V, but is able to withstand supply transients up to 30 V.

860 MHz, 17 dB gain power doubler amplifier

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List of components (see Fig.2)

COMPONENT	DESCRIPTION	VALUE
C1	ceramic multilayer capacitor	1 nF (max.)
C2	ceramic multilayer capacitor	1 nF
R	resistor	56 Ω, 2 W

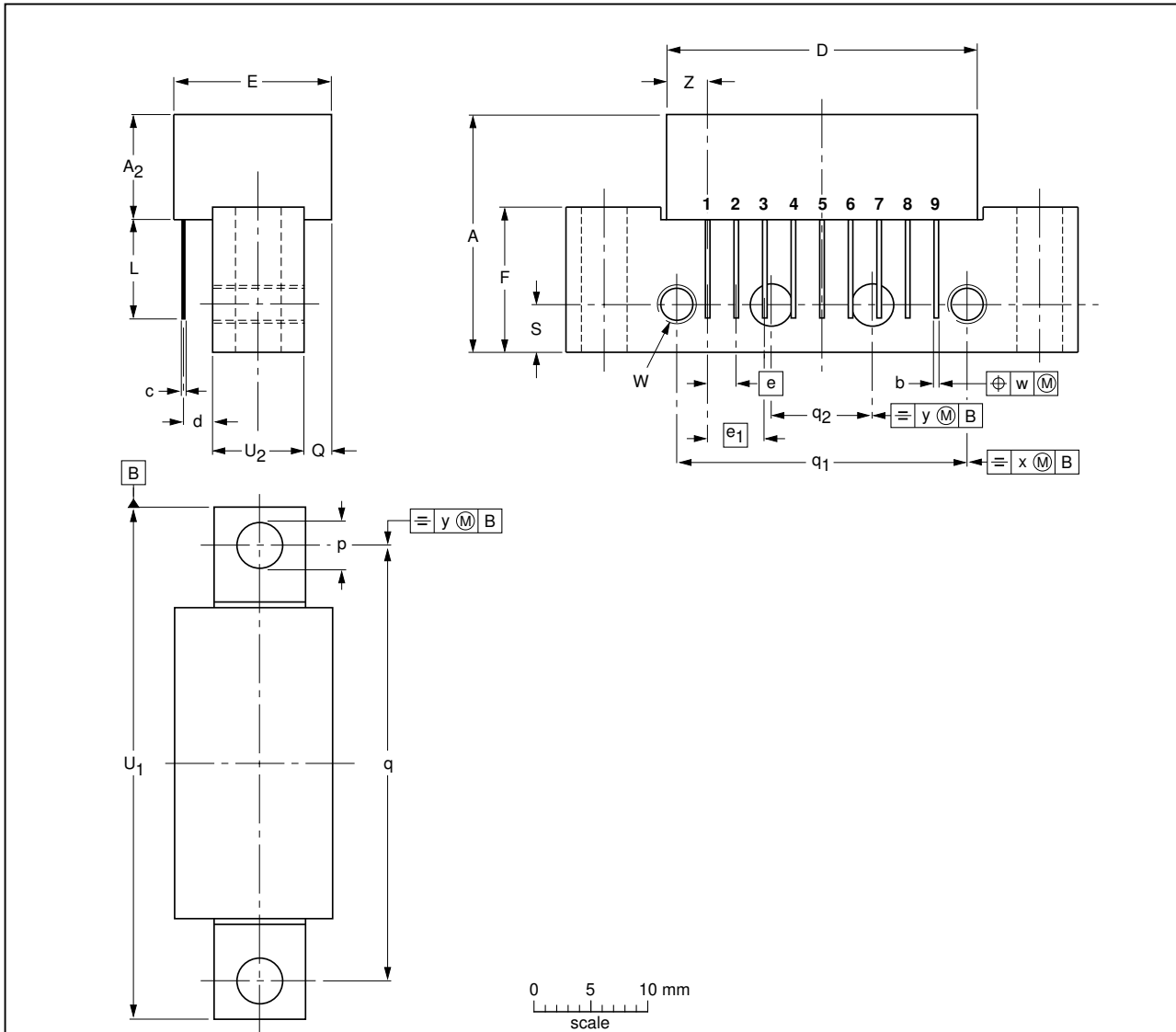
# 860 MHz, 17 dB gain power doubler amplifier

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## PACKAGE OUTLINE

Rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes; 9 gold-plated in-line leads

SOT115D



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>2</sub> max.	b	c	D max.	d max.	E max.	e	e <sub>1</sub>	F	L min.	p	Q max.	q	q <sub>1</sub>	q <sub>2</sub>	S	U <sub>1</sub>	U <sub>2</sub>	W	w	x	y	Z max.
mm	20.8	9.5	0.51 0.38	0.25	27.2	2.54	13.75	2.54	5.08	12.7	8.8	4.15 3.85	2.4	38.1	25.4	10.2	4.2	44.75 44.25	8.2 7.8	6-32 UNC	0.25	0.7	0.1	3.8

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT115D						04-02-04 10-06-18

860 MHz, 17 dB gain power doubler amplifier

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**DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## **Contact information**

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